

XPand6001

Natural Convection-Cooled Small Form Factor ATR Chassis for Ruggedized COM Express and PMC or XMC Modules

- ▶ Natural convection-cooled small form factor ATR chassis
- ▶ Physical dimensions of 4.88 in. (W), 2.10 in. (H), 7.70 in. (L)
- ▶ Supports a single ruggedized COM Express module
- ▶ Supports a single conduction-cooled PMC or XMC module
- ▶ Integration services with third-party modules available
- ▶ Optional 1.8 in. or Slim SATA SSD memory module
- ▶ Integrated MIL-STD-704 28V DC power supply
- ▶ Integrated MIL-STD-461 E/F EMI filtering
- ▶ Optional internal holdup
- ▶ Environmentally sealed
- ▶ D38999 connector support
- ▶ Configurable front panel I/O connectors
- ▶ Configurable I/O options
- ▶ Customizable internal carrier card for application specific circuitry
- ▶ Back panel power connector



XPand6001

The XPand6001 natural convection-cooled or conduction-cooled, fully-ruggedized ATR chassis is designed to meet the rigorous standards of MIL-STD-810 while integrating the latest power-saving, performance-enhancing, and space efficient off-the-shelf rugged technology. In today's avionics and ruggedized environments, size really does matter, and the XPand6001 sets a new standard for rugged small form factor computing systems.

The XPand6001 supports an internal carrier card that can be populated with a high-performance ruggedized COM Express module designed and manufactured by X-ES or a third party. The XPand6001 carrier card supports a PMC or XMC module, an SSD, and can also be customized to support application specific circuitry such as additional I/O or an FPGA. X-ES has an extensive lineup of PMC or XMC solutions to fulfill your data-processing and I/O requirements. Additionally, X-ES provides integration services for third-party ruggedized COM Express or PMC/XMC modules.

An optional 1.8 in. or Slim SATA SSD memory module (with optional integrated encryption) provides the convenience of high capacity off the shelf storage, the ruggedness of solid-state non-volatile memory, and the security of 256-bit AES encryption. X-ES maximizes power supply performance per cubic inch, supporting an integrated MIL-STD-704 28V DC power supply and MIL-STD-461 EMI filtering. Internal hold-up can be provided, as well.

Please contact X-ES sales to begin designing a system that will meet or exceed your I/O, processing, and power requirements.

X-ES

Extreme Engineering Solutions

...Always Fast

Extreme Engineering Solutions

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Physical Characteristics

Dimensions do not include connectors

- 4.88 in. (W), 2.10 in. (H), 7.70 in. (L)
- Weighs less than 3.75 pounds (fully populated)

Configuration Options

- Supports a single ruggedized COM Express module
- Supports a single conduction-cooled PMC or XMC module
- Customized carrier card solutions available for application specific circuitry
- 1.8 in. SSD module with optional integrated encryption

Front Panel I/O Options

- Up to two D38999 circular connectors for I/O
- Customizable connector options
- DVI graphics interfaces
- USB 2.0- and 1.0-compliant interfaces
- 10/100/1000BASE-T Gigabit Ethernet interfaces
- RS-232/RS-422 serial links
- MIL-STD-1553
- ARINC-429
- Custom I/O via XMC or PMC modules
- Custom I/O via carrier card

Power Supply Options

- Integrated power supply
- MIL-STD-704 28V DC input voltage support (default)
- MIL-STD-461 EMI filtering
- Integrated internal hold-up (optional)
- Additional power supply options available

Thermal

Rugged COM Express card with Core i7 Processor and 7.5 W XMC/PMC

- 55°C ambient with 40 W Rugged COM Express Card

